

# SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : **CL10F474ZB8NNNC**
- Descriptionnt : **CAP, 470nF, -20/+80%, 50V,Y5V,0603**

## A. Samsung Part Number

CL 10 F 474 Z B 8 N N N C  
 ①    ②    ③    ④    ⑤    ⑥    ⑦    ⑧    ⑨    ⑩    ⑪

① <b>Series</b>	Samsung Multi-layer Ceramic Capacitor				
② <b>Size</b>	0603 (inch code)	L: 1.6 ± 0.1 mm	W: 0.8 ± 0.1 mm		
③ <b>Dielectric</b>	Y5V	⑧ <b>Inner electrode</b>	Ni		
④ <b>Capacitance</b>	470 nF	⑨ <b>Termination</b>	Cu		
⑤ <b>Capacitance tolerance</b>	-20/+80 %	⑩ <b>Plating</b>	Sn 100% (Pb Free)		
⑥ <b>Rated Voltage</b>	50 V	⑪ <b>Product</b>	Normal		
⑦ <b>Thickness</b>	0.8 ± 0.1 mm	⑫ <b>Special</b>	Reserved for future use		
		⑬ <b>Packaging</b>	Cardboard Type, 7" reel		

## B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
<b>Capacitance</b>	Within specified tolerance	1kHz±10%    1.0±0.2Vrms
<b>Tan δ (DF)</b>	0.07 max.	
<b>Insulation Resistance</b>	10,000Mohm or 100Mohm·μF Whichever is Smaller	Rated Voltage    60~120 sec.
<b>Appearance</b>	No abnormal exterior appearance	Microscope (×10)
<b>Withstanding Voltage</b>	No dielectric breakdown or mechanical breakdown	250% of the rated voltage
<b>Temperature Characterisitcs</b>	Y5V (From -30℃ to 85℃, Capacitance change should be within -82~+22%)	
<b>Adhesive Strength of Termination</b>	No peeling shall be occur on the terminal electrode	500g·F, for 10±1 sec.
<b>Bending Strength</b>	Capacitance change : within ±30%	Bending to the limit (1mm) with 1.0mm/sec.
<b>Solderability</b>	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245±5℃, 3±0.3sec. (preheating : 80~120℃ for 10~30sec.)
<b>Resistance to Soldering heat</b>	Capacitance change : within ±20% Tan δ, IR : initial spec.	Solder pot : 270±5℃, 10±1sec.

	<b>Performance</b>	<b>Test condition</b>
<b>Vibration Test</b>	Capacitance change : within $\pm 20\%$ Tan $\delta$ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours $\times$ 3 direction (x, y, z)
<b>Moisture Resistance</b>	Capacitance change : within $\pm 30\%$ Tan $\delta$ : 0.09 max IR : 500Mohm or 25Mohm $\cdot \mu F$ Whichever is Smaller	With rated voltage 40 $\pm$ 2 $^{\circ}$ C, 90~95%RH, 500+12/-0hrs
<b>High Temperature Resistance</b>	Capacitance change : within $\pm 30\%$ Tan $\delta$ : 0.09 max IR : 1000Mohm or 50Mohm $\cdot \mu F$ Whichever is Smaller	With 200% of the rated voltage Max. operating temperature 1000+48/-0hrs
<b>Temperature Cycling</b>	Capacitance change : within $\pm 20\%$ Tan $\delta$ , IR : initial spec.	1 cycle condition Min. operating temperature $\rightarrow$ 25 $^{\circ}$ C $\rightarrow$ Max. operating temperature $\rightarrow$ 25 $^{\circ}$ C  5 cycle test

**C. Recommended Soldering method :**

Reflow ( Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.